

Title (en)

CONNECTION MODULE AND CONNECTION MODULE SYSTEM

Title (de)

VERBINDUNGSMODUL UND VERBINDUNGSMODULSYSTEM

Title (fr)

MODULE DE LIAISON ET SYSTÈME DE MODULE DE LIAISON

Publication

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Application

**EP 11790757 A 20111124**

Priority

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Abstract (en)

[origin: WO2012084407A1] The invention relates to a connection module (1; 2) and to a connection module system (10) for supplying electrical current to a drive module (5), comprising a housing (15), which has a second connection contact (58) arranged at a second opening (56) and a first connection contact (52) arranged at a first opening (51), wherein both the first and the second connection contact (52, 58) comprise a contact element (50, 55), wherein the second contact element (55) of the second connection contact (58) is arranged in a fixed manner in the housing (15) and the first contact element (50) of the first connection contact (52) is arranged movably in the housing (15), wherein the second contact element (55) of the second connection contact (58) is designed to provide a connection to a corresponding first contact element (50) of an adjacent module (2), wherein the second connection contact (58) comprises a spring terminal (60; 110), which is designed to press the corresponding first contact element (50) of the adjacent module (2) against the second contact element (55) of the second connection contact (58).

IPC 8 full level

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